TOSHIBA Field Effect Transistor Silicon P Channel MOS Type (U-MOSVI)

## **TPC8126**

# Lithium Ion Battery Applications Power Management Switch Applications

Small footprint due to small and thin package

• Low drain-source ON-resistance: RDS (ON) = 7.5 m $\Omega$  (typ.)

• Low leakage current:  $I_{DSS} = -10 \mu A \text{ (max) (V}_{DS} = -30 \text{ V)}$ 

• Enhancement mode:  $V_{th} = -0.8$  to -2.0 V ( $V_{DS} = -10$  V,  $I_{D} = -0.5$ mA)

#### Absolute Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	-30	V	
Drain-gate voltage ( $R_{GS} = 20 \text{ k}\Omega$ )		$V_{DGR}$	-30	V	
Gate-source voltage		V <sub>GSS</sub>	-25/ <del>+</del> 20	V	
Drain current	DC (Note 1)	I <sub>D</sub>	-11	А	
Diaili Cuitelli	Pulse (Note 1)	I <sub>DP</sub>	-44	A	
Drain power dissipatio	n (t = 10 s) (Note 2a)	PD	1.9	W	
Drain power dissipatio	n (t = 10 s) (Note 2b)	P <sub>D</sub>	1.0	W	
Single pulse avalanche energy (Note 3)		E <sub>AS</sub>	79	mJ	
Avalanche current	(Note 1)	I <sub>AR</sub>	-11	Α	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature range		T <sub>stg</sub>	-55 to 150	°C	

Note 1, Note 2, Note 3: See the next page.

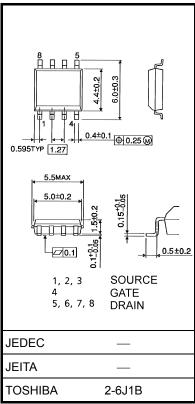
Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum

temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

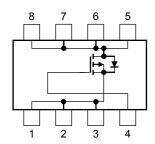
This transistor is an electrostatic-sensitive device. Handle with care.

Unit: mm



Weight: 0.080 g (typ.)

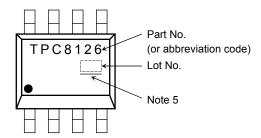
#### **Circuit Configuration**



#### **Thermal Characteristics**

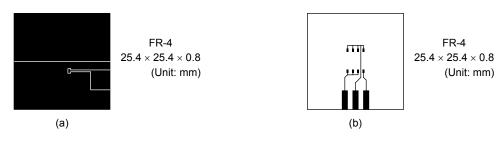
Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	R <sub>th (ch-a)</sub>	65.8	°C/W
Thermal resistance, channel to ambient (t = 10 s) (Note 2b)	R <sub>th (ch-a)</sub>	125	°C/W

#### Marking (Note 4)



Note 1: Ensure that the channel temperature does not exceed 150°C.

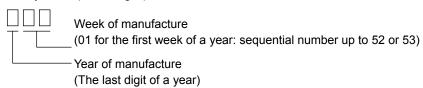
Note 2: (a)Device mounted on a glass-epoxy board (a) (b)Device mounted on a glass-epoxy board (b)



Note 3:  $V_{DD} = -24$  V,  $T_{ch} = 25$  °C (initial), L = 500  $\mu H$ ,  $R_G = 25$   $\Omega$ ,  $I_{AR} = -11$  A

Note 4: • on lower left of the marking indicates Pin 1.

Weekly code: (Three digits)



Note 5: A line under a Lot No. identifies the indication of product Labels.

Not underlined: [[Pb]]/INCLUDES > MCV

Underlined: [[G]]/RoHS COMPATIBLE or [[G]]/RoHS [[Pb]]

Please contact your TOSHIBA sales representative for details as to environmental matters such as the RoHS compatibility of Product. The RoHS is the Directive 2002/95/EC of the European Parliament and of the Council of 27 January 2003 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

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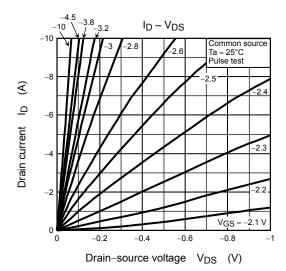
## Electrical Characteristics (Ta = 25°C)

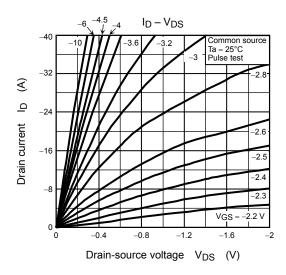
Char	acteristics	Symbol	Test Condition	Min	Min Typ. Max		Unit
Gate leakage curre	ent	I <sub>GSS</sub>	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±100	nA
Drain cut-OFF curr	ent	I <sub>DSS</sub>	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$	_	_	-10	μА
Drain aguras brasil	rdown voltage	V <sub>(BR) DSS</sub>	$I_D = -10 \text{ mA}, V_{GS} = 0 \text{ V}$	-30	_	_	V
Drain-source break	down voitage	V <sub>(BR) DSX</sub>	$I_D = -10 \text{ mA}, V_{GS} = 10 \text{ V}$ (Note 6)	-21	_	_	
Gate threshold volt	age	V <sub>th</sub>	$V_{DS} = -10 \text{ V}, I_D = -0.5 \text{ mA}$	-0.8 — -2.0		V	
Drain course ON r	naiatanaa	D	$V_{GS} = -4.5 \text{ V}, I_D = -5.5 \text{ A}$	<u> </u>		m()	
Drain-source ON-resistance		R <sub>DS</sub> (ON)	$V_{GS} = -10 \text{ V}, I_D = -5.5 \text{ A}$	_	7.5	10	mΩ
Input capacitance		C <sub>iss</sub>		_	— 2400 —		pF
Reverse transfer capacitance  Output capacitance		C <sub>rss</sub>	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	_	400	_	
·		Coss		_	460	_	
	Rise time	t <sub>r</sub>	V <sub>DS</sub> = -10 V, V <sub>GS</sub> = 0 V, f = 1 MHz  V <sub>GS</sub> = -10 V	_	8	_	- ns
0 " 1 " "	Turn-ON time	t <sub>on</sub>		_	16	_	
Switching time	Fall time	t <sub>f</sub>	4.75	_	65	_	
	Turn-OFF time	t <sub>off</sub>	$V_{DD} \approx -15 \text{ V}$ Duty ≤ 1%, $t_W = 10 \text{ μs}$	_	200	_	
Total gate charge (gate-source plus g	te-drain) $Q_g \qquad V_{DD} \approx -24 \text{ V, V}_{GS} = -10 \text{ V,}$		_				
Gate-source charge 1		Q <sub>gs1</sub>	$I_D = -11 \text{ A}$	_	5.6	_	nC
Gate-drain ("miller"	Gate-drain ("miller") charge			_	15		

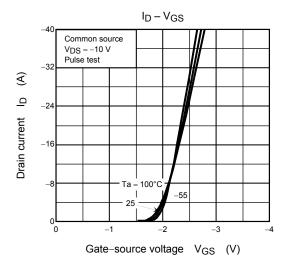
### **Source-Drain Ratings and Characteristics (Ta = 25°C)**

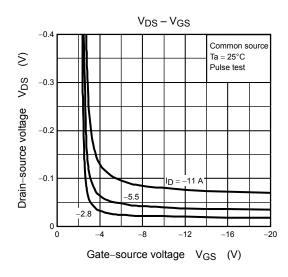
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit	
Drain reverse current	Pulse	(Note 1)	I <sub>DRP</sub>	_	_	_	-44	Α
Forward voltage (diode)		V <sub>DSF</sub>	I <sub>DR</sub> = -11 A, V <sub>GS</sub> = 0 V	_	_	1.2	V	

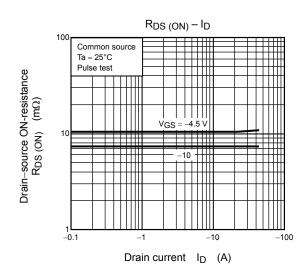
Note 6: VDSX mode (the application of a plus voltage between gate and source) may cause decrease in maximum rating of drain-source voltage.



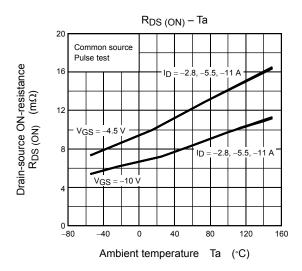


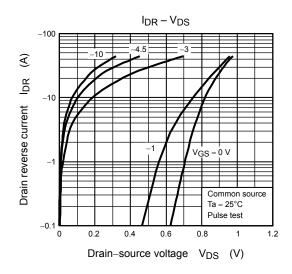


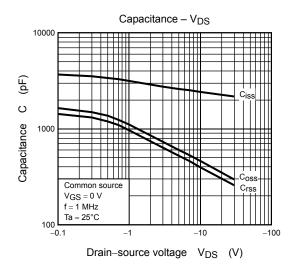


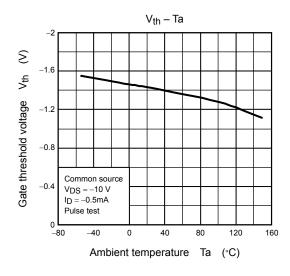


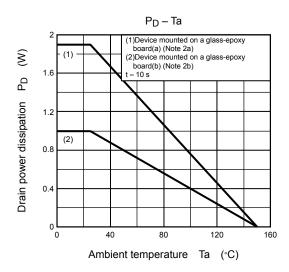
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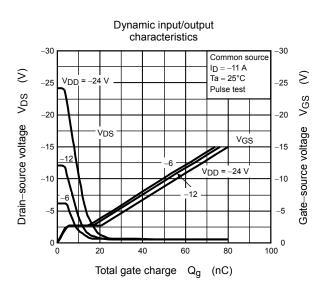




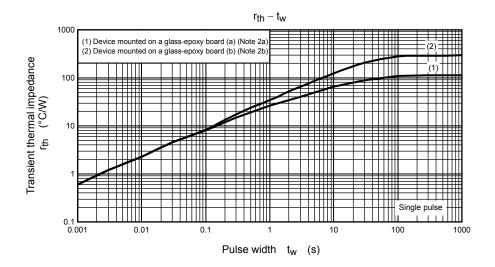


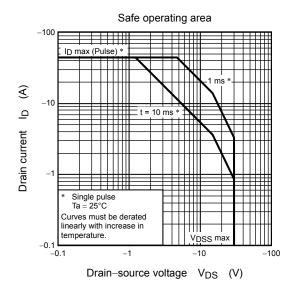






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